74HC1G04; 74HCT1G04

Inverter

Rev. 5 — 25 September 2013

Product data sheet

1. General description

The 74HC1G04; 74HCT1G04 is a single inverter. Inputs include clamp diodes that enable the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

2. Features and benefits

- Wide supply voltage range from 2.0 V to 6.0 V
- Input levels:
 - ◆ For 74HC1G04: CMOS level
 - ◆ For 74HCT1G04: TTL level
- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package							
	Temperature range	Name	Description	Version				
74HC1G04GW	–40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads;	SOT353-1				
74HCT1G04GW			body width 1.25 mm					
74HC1G04GV	–40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753				
74HCT1G04GV								



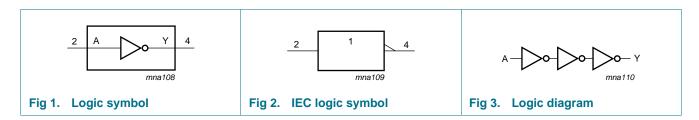
4. Marking

Table 2. Marking codes

Type number	Marking[1]
74HC1G04GW	HC
74HCT1G04GW	TC
74HC1G04GV	H04
74HCT1G04GV	T04

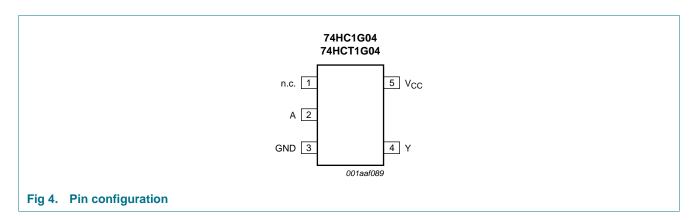
^[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A	2	data input
GND	3	ground (0 V)
Υ	4	data output
V _{CC}	5	supply voltage

74HC_HCT1G04

7. Functional description

Table 4. Function table

 $H = HIGH \ voltage \ level; \ L = LOW \ voltage \ level$

Input	Output
A	Υ
L	Н
H	L

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V). [1]

				(9.00	- /
Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
I _{IK}	input clamping current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{CC} + 0.5 \text{ V}$	-	±20	mA
I _{OK}	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	-	±20	mA
Io	output current	$-0.5 \text{ V} < \text{V}_{\text{O}} < \text{V}_{\text{CC}} + 0.5 \text{ V}$	-	±12.5	mA
I _{CC}	supply current		-	25	mA
I_{GND}	ground current		-25	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$	[2] _	200	mW

^[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74HC1G04			74HCT1G04			Unit
			Min	Тур	Max	Min	Тур	Max	
V_{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
VI	input voltage		0	-	V_{CC}	0	-	V_{CC}	V
Vo	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	$V_{CC} = 2.0 \text{ V}$	-	-	625	-	-	-	ns/V
		V _{CC} = 4.5 V	-	-	139	-	-	139	ns/V
		V _{CC} = 6.0 V	-	-	83	-	-	-	ns/V

^[2] Above 55 °C, the value of P_{tot} derates linearly with 2.5 mW/K.

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V). All typical values are measured at T_{amb} = 25 °C.

Symbol	Parameter	Conditions	-40	–40 °C to +85 °C			-40 °C to +125 °C	
			Min	Тур	Max	Min	Max	
For type	74HC1G04							
V _{IH}	HIGH-level input	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	V
	voltage	V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	V
V_{IL}	LOW-level input	V _{CC} = 2.0 V	-	8.0	0.5	-	0.5	V
	voltage	V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	V
V _{OH}	HIGH-level output	$V_I = V_{IH}$ or V_{IL}						
	voltage	$I_O = -20 \mu A; V_{CC} = 2.0 V$	1.9	2.0	-	1.9	-	V
		$I_O = -20 \mu A; V_{CC} = 4.5 V$	4.4	4.5	-	4.4	-	V
		$I_O = -20 \mu A; V_{CC} = 6.0 V$	5.9	6.0	-	5.9	-	V
		$I_{O} = -2.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	4.13	4.32	-	3.7	-	V
		$I_{O} = -2.6 \text{ mA}; V_{CC} = 6.0 \text{ V}$	5.63	5.81	-	5.2	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}						
		$I_O = 20 \mu A$; $V_{CC} = 2.0 \text{ V}$	-	0	0.1	-	0.1	V
		$I_O = 20 \mu A$; $V_{CC} = 4.5 V$	-	0	0.1	-	0.1	V
		$I_O = 20 \mu A$; $V_{CC} = 6.0 \text{ V}$	-	0	0.1	-	0.1	V
		$I_O = 2.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.15	0.33	-	0.4	V
		$I_O = 2.6 \text{ mA}; V_{CC} = 6.0 \text{ V}$	-	0.16	0.33	-	0.4	V
I _I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 \text{ V}$	-	-	1.0	-	1.0	μΑ
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0 \text{ V}$	-	-	10	-	20	μΑ
Cı	input capacitance		-	1.5	-	-	-	pF
For type	74HCT1G04							
V _{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	1.6	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	1.2	8.0	-	0.8	V
V _{OH}	HIGH-level output	$V_I = V_{IH}$ or V_{IL}						
	voltage	$I_{O} = -20 \mu A$; $V_{CC} = 4.5 \text{ V}$	4.4	4.5	-	4.4	-	V
		$I_{O} = -2.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	4.13	4.32	-	3.7	-	V
V _{OL}	LOW-level output	$V_I = V_{IH}$ or V_{IL}						
	voltage	$I_O = 20 \mu A$; $V_{CC} = 4.5 \text{ V}$	-	0	0.1	-	0.1	V
		$I_O = 2.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.15	0.33	-	0.4	V
I _I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	1.0	-	1.0	μΑ

 Table 7.
 Static characteristics ...continued

Voltages are referenced to GND (ground = 0 V). All typical values are measured at T_{amb} = 25 °C.

Symbol Parameter		Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Тур	Max	Min	Max	
I _{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	10	-	20	μΑ
ΔI_{CC}	additional supply current	per input; $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V};$ $V_{I} = V_{CC} - 2.1 \text{ V}; I_{O} = 0 \text{ A}$	-	-	500	-	850	μΑ
Cı	input capacitance		-	1.5	-	-	-	pF

11. Dynamic characteristics

Table 8. Dynamic characteristics

GND = 0 V; $t_r = t_f \le 6.0$ ns; All typical values are measured at $T_{amb} = 25$ °C. For test circuit, see <u>Figure 6</u>

Symbol	Parameter	Conditions		-40	°C to +8	5 °C	-40 °C to +125 °C		Unit
				Min	Тур	Max	Min	Max	
For type	74HC1G04		'				'	'	
t _{pd}	propagation delay	A to Y; see Figure 5	<u>[1]</u>						
		$V_{CC} = 2.0 \text{ V}; C_L = 50 \text{ pF}$		-	25	105	-	135	ns
		$V_{CC} = 4.5 \text{ V}; C_L = 50 \text{ pF}$		-	9	21	-	27	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		-	7	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}; C_L = 50 \text{ pF}$		-	8	18	-	23	ns
C_{PD}	power dissipation capacitance	$V_I = GND$ to V_{CC}	[2]	-	16	-	-	-	pF
For type	74HCT1G04								
t _{pd}	propagation delay	A to Y; see Figure 5	<u>[1]</u>						
		$V_{CC} = 4.5 \text{ V}; C_L = 50 \text{ pF}$		-	10	24	-	27	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$		-	8	-	-	-	ns
C_{PD}	power dissipation capacitance	$V_I = GND \text{ to } V_{CC} - 1.5 \text{ V}$	[2]	-	18	-	-	-	pF

^[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz

f_o = output frequency in MHz

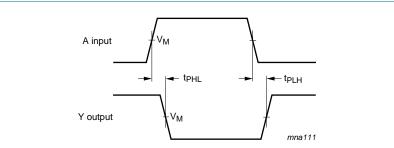
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs

^[2] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

12. Waveforms

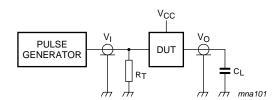


Measurement points are given in Table 9.

Fig 5. The input (A) to output (Y) propagation delays

Table 9. Measurement points

Туре	V _I	V _M
74HC1G04	GND to V _{CC}	$0.5 \times V_{CC}$
74HCT1G04	GND to 03 V	1.3 V



Test data is given in Table 8. Definitions for test circuit:

 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

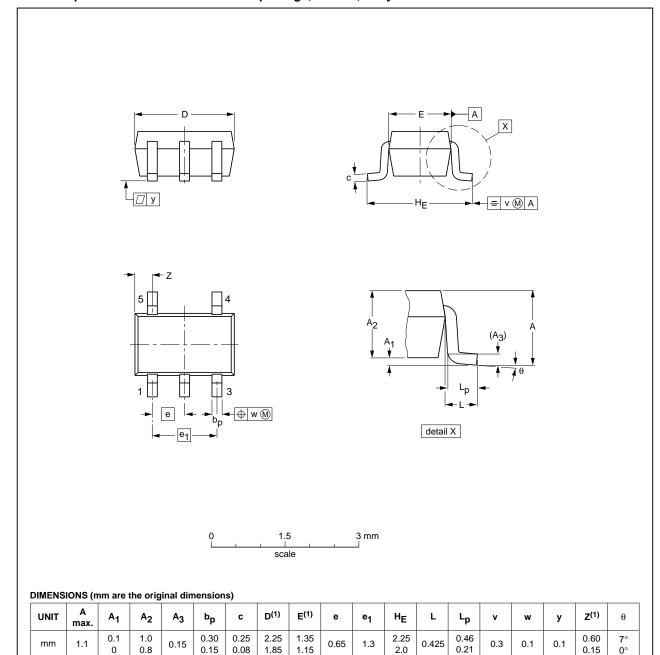
 C_L = Load capacitance including jig and probe capacitance

Fig 6. Load circuitry for switching times

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



Nata

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT353-1		MO-203	SC-88A			-00-09-01 03-02-19	

Fig 7. Package outline SOT353-1 (TSSOP5)

74HC_HCT1G04

Plastic surface-mounted package; 5 leads

SOT753

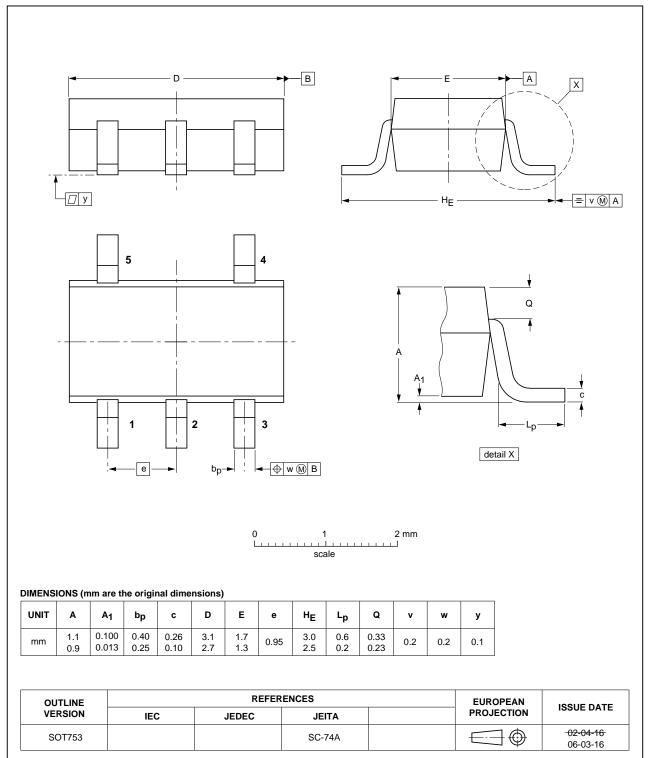


Fig 8. Package outline SOT753 (SC-74A)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
DUT	Device Under Test
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

	•					
Document ID	Release date	Data sheet status	Change notice	Supersedes		
74HC_HCT1G04 v.5	20130925	Product data sheet	-	74HC_HCT1G04 v.4		
Modifications:	Section 1 "	General description" updated.				
74HC_HCT1G04 v.4	20070716	Product data sheet	-	74HC_HCT1G04 v.3		
Modifications:	 The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. 					
	 Legal texts have been adapted to the new company name where appropriate. 					
	 Package SOT353 changed to SOT353-1 in <u>Table 1</u> and <u>Figure 7</u>. 					
	 Quick Reference Data and Soldering sections removed. 					
	 Section 2 "Features and benefits" updated. 					
74HC_HCT1G04 v.3	20020517	Product specification	-	74HC_HCT1G04 v.2		
74HC_HCT1G04 v.2	20010302	Product specification	-	74HC_HCT1G04 v.1		
74HC_HCT1G04 v.1	19980831	Preliminary specification	-	-		

16. Legal information

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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74HC_HCT1G04

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18. Contents

1	General description
2	Features and benefits
3	Ordering information 1
4	Marking 2
5	Functional diagram 2
6	Pinning information
6.1	Pinning
6.2	Pin description 2
7	Functional description 3
8	Limiting values 3
9	Recommended operating conditions 3
10	Static characteristics 4
11	Dynamic characteristics 5
12	Waveforms 6
13	Package outline
14	Abbreviations9
15	Revision history9
16	Legal information
16.1	Data sheet status
16.2	Definitions
16.3	Disclaimers
16.4	Trademarks11
17	Contact information 11
18	Contents

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